



Product Overview

Resin Bond 320

Innerlayer Adhesion Promoter

Product Description

Resin Bond 320 is a concentrated microetch additive designed to promote innerlayer bonding. Resin Bond 320 offers several benefits over other "oxide alternatives" currently available. Resin Bond 320 provides excellent bond strength across a wide range of resin systems. Resin Bond 320 develops the desired surface with shorter dwell times and less copper removal to provide higher process throughput at lower operating costs.

Features

- 💡 Effective at very low operating concentrations
- 💡 Rate enhancing additives
- 💡 Etch modifiers

Benefits

- 💰 Reduces operating cost through decreased consumption
- ⚙️ Faster etch rates, shorter dwell times, greater throughput
- 👉 Develops desired surface with less copper removal

Physical Properties

Specific gravity: 1.15
pH: <2
Appearance: clear to amber color
Freezing point: <45 °F

Typical Process Cycle

ALC-1 Alkaline Cleaner
Triple Cascade DI Water Rinse
Resin Bond 320 Pre-dip
Resin Bond 320 Etching Solution
Triple Cascade DI Water Rinse
Dryer

Safety

Avoid contact with eyes, skin and clothing. Wear chemical handler's gloves, goggles and protective clothing when handling. Read and understand Material Safety Data Sheet before using this product.

Notice

The information and recommendations, contained herein, regarding this product are, to the best of our knowledge, true and accurate. We make no guarantee of results because the conditions of actual use are beyond our control. We assume no liability for damages or penalties resulting from the use of this product or following our recommendations. Our recommendations and suggestions for use of this product are not intended to grant license to operate under or infringe any patent.